Product Change Notification: CAAN-22ETOA843

Date:

06-Oct-2026

Product Category:

Memory

Notification Subject:

CCB 8548 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for 47L04T-E/SN, 47L04T-I/SN, 47L04-I/SN, 47L04-E/SN, 47C04T-E/SN, 47C04T-I/SN, 47C04-I/SN, 47C04-E/SN, 47L16T-E/SN, 47L16T-I/SN, 47L16-I/SN, 47L16-E/SN, 47C16T-E/SN, 47C16T-I/SN, 47C16-I/SN and 47C16-E/SN catalog part numbers (CPN) available in 8L SOIC (.150in) package at MTAI assembly site.

Affected CPNs:

CAAN-22ETOA843_Affected_CPN_10062026.pdf
CAAN-22ETOA843_Affected_CPN_10062026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for 47L04T-E/SN, 47L04T-I/SN, 47L04-I/SN, 47L04-E/SN, 47C04T-E/SN, 47C04T-I/SN, 47C04-I/SN, 47C04-E/SN, 47L16T-E/SN, 47L16T-I/SN, 47L16-I/SN, 47L16-E/SN, 47C16T-E/SN, 47C16T-I/SN, 47C16-I/SN and 47C16-E/SN catalog part numbers (CPN) available in 8L SOIC (.150in) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change**
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No

Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-Free)	8390A (PFAS-Free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 18 December 2026 (date code: 2651)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	**December 2026**				
Work Week	40	41	42	43	44		49	50	51	52	53
Qual Report Availability		X									
Final PCN Issue Date		X									
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB#2925.

Revision History: October 06, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-22ETOA843_Qual Report_CCB 2925.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

47L04T-E/SN

47L04T-I/SN

47L04-I/SN

47L04-E/SN

47C04T-E/SN

47C04T-I/SN

47C04-I/SN

47C04-E/SN

47L16T-E/SN

47L16T-I/SN

47L16-I/SN

47L16-E/SN

47C16T-E/SN

47C16T-I/SN

47C16-I/SN

47C16-E/SN



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-22ETOA843

Date

July 07, 2017

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for 47L04T-E/SN, 47L04T-I/SN, 47L04-I/SN, 47L04-E/SN, 47C04T-E/SN, 47C04T-I/SN, 47C04-I/SN, 47C04-E/SN, 47L16T-E/SN, 47L16T-I/SN, 47L16-I/SN, 47L16-E/SN, 47C16T-E/SN, 47C16T-I/SN, 47C16-I/SN and 47C16-E/SN catalog part numbers (CPN) available in 8L SOIC (.150in) package at MTAI assembly site.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for 47L04T-E/SN, 47L04T-I/SN, 47L04-I/SN, 47L04-E/SN, 47C04T-E/SN, 47C04T-I/SN, 47C04-I/SN, 47C04-E/SN, 47L16T-E/SN, 47L16T-I/SN, 47L16-I/SN, 47L16-E/SN, 47C16T-E/SN, 47C16T-I/SN, 47C16-I/SN and 47C16-E/SN catalog part numbers (CPN) available in 8L SOIC (.150in) package at MTAI assembly site.

CN:	ES098787
QUAL ID:	Q17082
MP CODE:	DEDX2YC2XA00
Part No.:	24LC512T-E/SN
Bonding No.:	BDM-001299 Rev. A
CCB No.:	2925

Lead Frame

Paddle Size:	95 x 130 mils
Material:	CDA194
DAP Surface Prep:	Bare Cu on paddle
Process:	Stamped
Lead Lock:	Yes
Part Number:	10100842
Lead Plating:	Matte Tin
Treatment:	Roughened

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	8390A

Mold Compound

Mold Compound:	G600V

Package

Type:	8L SOIC
Package Size:	150 mils

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI180702624.000	GRSM417152115.330	1719PE9
MTAI180703100.000	GRSM417152115.330	1719U57
MTAI180703104.000	GRSM417152115.340	1719UBP

Result: **Pass**

Conclusion:

8L SOIC (.150”) assembled by MTAI pass reliability test per QCI-39000.This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243	IPC/JEDEC J-STD-020D	135	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test :**+25°C,85°C and 125°C **System:** NEXTEST_PT Bake 150°C, 24 hrs **System:** CHINEE 85°C/85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243 **Electrical Test :**+25°C,85°C and 125°C **System:** NEXTEST_PT	JESD22-A113	693(0)	0/693	Pass	Good Devices
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles **System :** TABAI ESPEC TSA-70H	JESD22-A104	231			Parts had been pre-conditioned at 260°C
	Electrical Test: + 125°C **System:** NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
	Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118	231			Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C **System:** NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts **System:** HAST 6000X	JESD22-A110	231			Parts had been pre-conditioned at 260°C
	Electrical Test:+ 25°C,85°C and 125°C **System:** NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs **System:** SHEL LAB **Electrical Test :**+25°C,85°C and 125°C **System:** NEXTEST_PT	JESD22-A103	45(0)	0/45	Pass	45 units
Solderability Temp 215°C	**Steam Aging:** Temp 93°C,8Hrs **System:** SAS-3000 **Solder Dipping:** Solder Temp.215°C **Solder material:** SnPb Sn63,Pb37 **System:** ERSA RA 2200D **Visual Inspection:** External Visual Inspection	JESD22B-102 E	22 (0)	0/22	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result
Solderability Temp 245°C	**Steam Aging:** Temp 93°C,8Hrs **System:** SAS-3000 **Solder Dipping:**Solder Temp.245°C **Solder material:**Pb Free Sn 95.5Ag3.9 Cu0.6 **System:** ERSA RA 2200D **Visual Inspection:** External Visual Inspection	JESD22B-102 E	22 (0)	0/22	Pass
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0)	0/30	Pass
	Bond Shear (>15.00 grams)	JESD22-B116	30 (0)	0/30	Pass